

# unicore UM980 All Constellation Multi Frequency High Precision RTK Positioning Module Instruction Manual

Home » unicore v unicore UM980 All Constellation Multi Frequency High Precision RTK Positioning Module Instruction Manual



#### **Contents**

- 1 UM980 All Constellation Multi Frequency High Precision RTK Positioning Module
- 2 Revision History
- 3 Foreword
- 4 Introduction
- 5 Hardware
- **6 Hardware Design**
- **7 Production Requirement**
- 8 Packaging
- 9 Documents / Resources
  - 9.1 References
- 10 Related Posts

UM980 All Constellation Multi Frequency High Precision RTK Positioning Module



INSTALLATION AND OPERATION
USER MANUAL
WWW.UNICORECOMM.COM

### **UM980**

BDS/GPS/GLONASS/Galileo/QZSS All-constellation Multi-frequency High Precision RTK Positioning Module Copyright© 2009-2023, Unicore Communications, Inc. Data subject to change without notice.

## **Revision History**

Version	Revision History	Date
R1.0	First release	2022-08
R1.1	If hot start is not used, V_BCKP should be connected to VCC; Update the IO threshold in Table 2-4; Add section 3.1: UM980 minimal design; Update the recommended thickness of the stencil in Chapter 4	2022-10
R1.2	Update the supported frequencies; Update the TTFF; Add chapter 3.5: Recommended PCB Package Design; Optimize Chapter 3.2 Antenna Feed Design; Optimize Chapter 3.3 Power-on and Power-off	2023-04

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#### **Foreword**

This document describes the information of the hardware, package, specification and the use of Unicore UM980 modules.

## **Target Readers**

This document applies to technicians who possess the expertise on GNSS receivers.

## Introduction

UM980 is a new generation of GNSS high precision RTK positioning module from Unicore. It supports all constellations and all frequencies, and can simultaneously track BDS B1l/B2l/B3l/B1C/B2a/B2b, GPS L1/L2/L5, GLONASS G1/G2/G3, Galileo E1/E5a/E5b/E6, QZSS L1/L2/L5, NavIC L5 and SBAS. The module is mainly used in surveying and mapping, precise agriculture, UAVs, and autonomous robots. UM980 is based on NebulasIVTM, a GNSS SoC which integrates the RF-baseband and high precision algorithm. Besides, the SoC integrates a dual-core CPU, a high speed floating point processor and an RTK co-processor with 22 nm low power design, and it supports 1408 super channels. All these above enable stronger signal processing. With the built-in JamShield adaptive anti-jamming technology, UM980 can fulfill a strengthening RTK engine solution of multi-mode multi-frequency, which ensures a good performance on RTK initialization speed, measurement accuracy and reliability even in the most challenging environments such as urban canyons and tree shades. Furthermore, UM980 supports abundant interfaces such as UART, I 2 \* C , SPI \* , as well as 1PPS, EVENT, CAN \* , which meets the customers' needs in different applications.



Figure 1-1 UM980 Module

## 1.1 Key Features

- Based on the new generation GNSS SoC -NebulasIVTM , with RF-baseband and high precision algorithm integrated
- 17 mm × 22 mm × 2.6 mm, surface-mount device
- Supports all-constellation multi-frequency on-chip RTK positioning solution
- Supports BDS B1I/B2I/B3I/B1C/B2a/B2b + GPS L1/L2/L5 + GLONASS G1/G2/G3 + Galileo E1/E5a/E5b/E6 + QZSS L1/L2/L5 + NavIC L5 + SBAS
- All-constellation multi-frequency RTK engine and advanced RTK processing technology
- · Instantaneous RTK initialization technology
- Independent tracking of different frequencies, and 60 dB narrowband anti-jamming technology

## 1.2 Key Specifications Table 1-1 Technical Specifications

Basic Information	
Channels	1408 channels, based on NebulasIV
Constellations	BDS/GPS/GLONASS/G alileo/QZSS
Frequencies	BDS: B1I, B2I, B3I, B1 C, B2a, B2b GPS: L1 C/A, L1C, L2P (Y), L2C, L5 GLONASS: G1, G2, G3 Galileo: E1, E5a, E5b, E6 QZSS: L1, L2, L5 NavIC: L5
Power	
Voltage	+3.0 V ~ +3.6 V DC
Power Consumption	480 mW (Typical)

## **Performance**

	Single Point Positioning		Horizontal: 1.5 m		
	) (RMS)		Vertical: 2.5 m		
Positioning Accuracy	DGPS (RMS)	110	Horizontal: 0.4 m		
Positioning Accuracy	DGF3 (NIVIS)	112	Vertical: 0.8 m		
	RTK (RMS)1	2	Horizontal: 0.8 cm +	1 ppm	
		_	Vertical: 1.5 cm + 1 ppm		
Observation Accuracy (RMS)	BDS	GPS	GLONASS	Galileo	
BB/BIC/LIG/Li C/A/GI/EI Pseudorange	10 cm	10 cm	10 cm	10 cm	
B11/B1C/L1C/L1 C/A/GI/EI Carrier Phase	1mm	1mm	1mm	1mm	
B3I/L2P(Y)/L2C/G2/E6 Pseudorange	10 cm	10 cm	10 cm	10 cm	
B31/12P(Y)/L2C/G2/E6 Carrier Phase	1mm	1mm	1mm	1mm	
B2I/B2a/B2b/L5/G3/E5a/E5b Pseudorange	10 cm	10 cm	10 cm	10 cm	
B21/B2a/B2b/L5/G3/E5a/E5b Carrier Phas e	1mm	1mm	1mm	1mm	
Time Pulse Accuracy (RMS)	20 ns				
Velocity Accuracy3 (RMS)	0.03 m/s				

1. Test results may be biased due to atmospheric conditions, baseline length, GNSS antenna type, multipath, number of visible satellites, and satellite geometry

- 2. The measurement uses a 1 km baseline and a receiver with good antenna performance, regardless of possible errors of antenna phase center offset
- 3. Open sky, unobstructed scene, 99% @ static

Time a As Final Final (TTFF)	Cold Start < 12 s
Time to First Fix4 (TTFF)	Hot Start < 4 s
Initialization Time1	< 5 s (Typical)
Initialization Reliability1	> 99.9%
Data Update Rate	50 Hz5 Positioning
Differential Data	RTCM 3.X
Data Format	NMEA-0183, Unicore
Physical Characteristics	
Package	54 pin LGA
Dimensions	22 mm × 17 mm × 2.6 mm
Weight	1.88 g ± 0.03 g
Environmental Specifications	
Operating Temperature	-40 °C ~ +85 °C
Storage Temperature	-55 °C ~ +95 °C
Humidity	95% No condensation
Vibration	GJB150.16A-2009, MIL-STD-810F
Shock	GJB150.18A-2009, MIL-STD-810F
Functional Ports	
UART × 3	
21*C ×1	
SPI* × 1	Slave
CAN * × 1	Shared with UART3

<sup>\*</sup> I 2 C, SPI, CAN: reserved interfaces, not supported currently

<sup>4 -130</sup>dBm @ more than 12 available satellites

<sup>5</sup> Supports 50 Hz after firmware upgrade

<sup>1.3</sup> Block Diagram

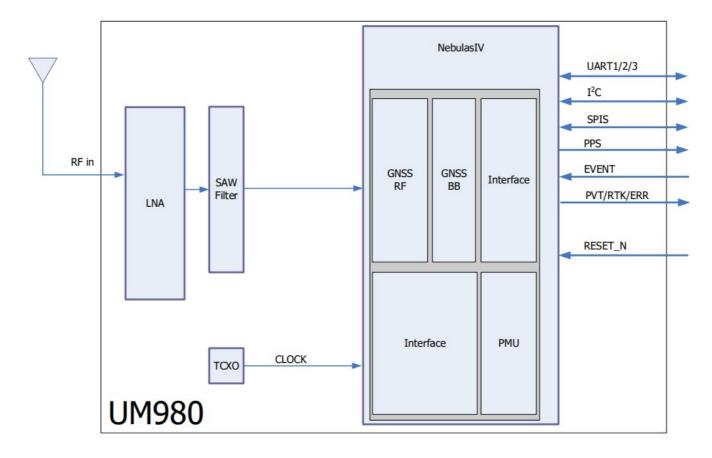


Figure 1-2 UM980 Block Diagram

## RF Part

The receiver gets filtered and enhanced GNSS signal from the antenna via a coaxial cable. The RF part converts the RF input signals into the IF signals, and converts IF analog signals into digital signals required for NebulasIV TM chip (UC9810).

## • NebulasIVTM SoC (UC9810)

NebulasIV (UC9810) is UNICORECOMM's new generation high precision GNSS SoC with 22 nm low power design, supporting all constellations all frequencies and 1408 super channels. It integrates a dual-core CPU, a high speed floating point processor and an RTK co-processor, which can fulfill the high precision baseband processing and RTK positioning independently.

## External Interfaces

The external interfaces of UM980 include UART, I 2 \* C, SPI \*, CAN \*, PPS, EVENT, RTK\_STAT, PVT\_STAT, ERR\_STAT, RESET\_N, etc.

## **Hardware**

## 2.1 Pin Definition

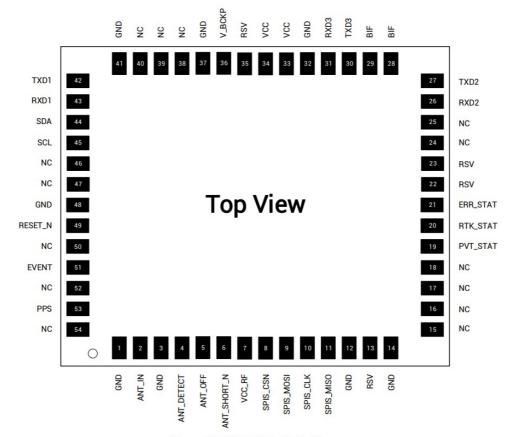


Figure 2-1 UM980 Pin Definition

**Table 2-1 Pin Description** 

No.	Pin	I/O	Description
1	GND	_	Ground
2	ANT_IN	1	GNSS antenna signal input
3	GND	_	Ground
4	ANT_DETE CT	1	Antenna signal detection
5	ANT_OFF	0	Disable external LNA
6	ANT_SHOR T_N	1	Antenna short circuit detection; active low
7	VCC_RF6	0	External LNA power supply
8	SPIS_CSN	I	Chip select pin for SPI slave
9	SPIS_MOSI	I	Master Out / Slave In. This pin is used to receive data in slave mode.
10	SPIS_CLK	I	Clock input pin for SPI slave
11	SPIS_MISO	0	Master In / Slave Out. This pin is used to transmit data in slave mode.
12	GND	_	Ground
13	RSV	_	Reserved
14	GND	_	Ground
15	NC		No connection inside

16       NC       —       No connection inside         17       NC       —       No connection inside         18       NC       —       No connection inside         19       PVT_STAT       O       PVT status: active high; outputs high when positioning and low when not positioning         20       RTK_STAT       O       RTK status: active high; outputs high for RTK fixed solution and low for other positioning no positioning         21       ERR_STAT       O       Error status: active high; outputs high when failing self-test, an when passing self-test	
18 NC — No connection inside  19 PVT_STAT O PVT status: active high; outputs high when positioning and low when not positioning  20 RTK_STAT O RTK status: active high; outputs high for RTK fixed solution and low for other positioning no positioning  Error status: active high; outputs high when failing self-test, an	
PVT_STAT O PVT status: active high; outputs high when positioning and low when not positioning  RTK status: active high; outputs high for RTK fixed solution and low for other positioning no positioning  Error status: active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high; outputs high when failing self-test, and status active high;	
outputs high when positioning and low when not positioning  RTK status: active high; outputs high for RTK fixed solution and low for other positioning  RTK_STAT O  Error status: active high; outputs high when failing self-test, an	
20 RTK_STAT O outputs high for RTK fixed solution and low for other positioning no positioning  Error status: active high; outputs high when failing self-test, and self-test are status.	
21   FBB SIAI   ()	g status or
	d low
22 RSV — Reserved, recommended to be floating	
23 RSV — Reserved, recommended to be floating	
24 NC — No connection inside	
25 NC — No connection inside	
26 RXD2 I COM2 input, LVTTL level	
27 TXD2 O COM2 output, LVTTL level	
Built-in function; recommended to add a through-hole testing p 10 kΩ pullup resistor; cannot connect ground or power supply, and cannot input/output data, but can be floating	point and a
Built-in function; recommended to add a through-hole sting portion of the sting portion of t	
30 TXD3 O COM3 output, which can be used as CAN TXD, LVTTL level	
31 RXD3 I COM3 input, which can be used as CAN RXD, LVTTL level	
32 GND — Ground	
33 VCC I Power supply	
34 VCC I Power supply	
35 RSV — Reserved	
When the main power supply VCC is cut off, V_BCKP supplies RTC and relevant register. Level requirement: 2.0 V ~ 3.6 V, at working current should be less than 60 µA at 25 °C. If you do not start function, connect V_BCKP to VCC. Do NOT connect or leave it floating.	nd the not use the
37 GND — Ground	
38 NC — No connection inside	
39 NC — No connection inside	
40 NC — No connection inside	
41 GND — Ground	

42	TXD1	0	COM1 output, LVTTL level
43	RXD1	1	COM1 input, LVTTL level
44	SDA	I/O	I2 C data
45	SCL	I/O	I2C clock
46	NC	_	No connection inside
47	NC	_	No connection inside
48	GND	_	Ground
49	RESET_N	1	System reset; active Low. The active time should be no less than 5 ms.
50	NC	_	No connection inside
51	EVENT	I	Event mark input, with adjustable frequency and polarity
52	NC	_	No connection inside
53	PPS	0	Pulse per second, with adjustable pulse width and polarity
54	NC	_	No connection inside

## 2.2 Electrical Specifications

## 2.2.1 Absolute Maximum Ratings

Table 2-2 Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Power Supply Voltage	VCC	-0.3	3.6	V
Input Voltage	Vin	-0.3	3.6	V
GNSS Antenna Signal Input	ANT_IN	-0.3	6	V
Antenna RF Input Power	ANT_IN input power		10	dBm
External LNA Power Supply	VCC_RF	-0.3	3.6	V
VCC_RF Output Current	ICC_RF		100	mA
Storage Temperature	Tstg	-55	95	° C

**2.2.2 Operating Conditions**Table 2-3 Operating Conditions

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Power Supply Voltage7	VCC	3	3.3	3.6	V	
Maximum VCC Ripple	Vrpp	0		50	mV	
Working Current 8	lopr		145	180	mA	VCC=3.3 V

- 6 Not recommended to take VCC\_RF as ANT\_BIAS to feed the antenna. See section 3.2 for more
- 7 The voltage range of VCC (3.0 V  $\sim$  3.6 V) has already included the ripple voltage.
- 8 Since the product has capacitors inside, inrush current occurs during power-on. You should evaluate in the actual environment in order to check the effect of the supply voltage drop caused by inrush

Parameter	Symbol	Min.	Тур.	Max.	Unit C
VCC_RF Output Voltage	VCC_RF		VCC-0.1		V
VCC_RF Output Current	ICC_RF			50	mA
Operating Temperature	Topr	-40		85	° C
Power Consumption	Р		480		mW

## 2.2.3 IO Threshold

Table 2-4 IO Threshold

Parameter	Symbol	Min.	Тур.	Max.	Unit C	Condition
Low Level Input Voltage	Vin_low	0		0.6	V	
High Level Input Voltage	Vin_high	VCC × 0.7		VCC + 0.2	V	
Low Level Output Voltage	Vout_low	0		0.45	V	lout = 2 mA
High Level Output Voltage	Vout_high	VCC - 0.45		VCC	V	lout = 2 mA

## 2.2.4 Antenna Feature

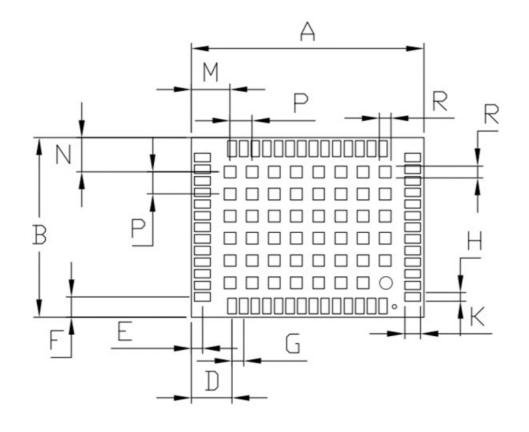
Table 2-5 Antenna Feature

Parameter	Symbol	Min.	Тур.	Max.	Unit C	Condition
Optimum Input Gain	Gant	18	30	36	dB	

## 2.3 Dimensions

Table 2-6 Dimensions

Parameter	Min. (mm)	Typ. (mm)	Max. (mm)
А	21.80	22.00	22.50
В	16.80	17.00	17.50
С	2.40	2.60	2.80
D	3.75	3.85	3.95
E	0.95	1.05	1.15
F	1.80	1.90	2.00
G	1.00	1.10	1.20
Н	0.70	0.80	0.90
K	1.40	1.50	1.60
М	3.55	3.65	3.75
N	3.15	3.25	3.35
Р	2.00	2.10	2.20
R	1.00	1.10	1.20
Х	0.72	0.82	0.92



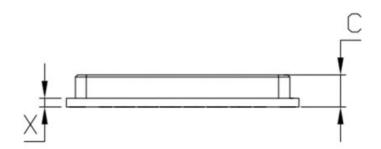


Figure 2-2 UM980 Mechanical Dimensions

## **Hardware Design**

## 3.1 Recommended Minimal Design

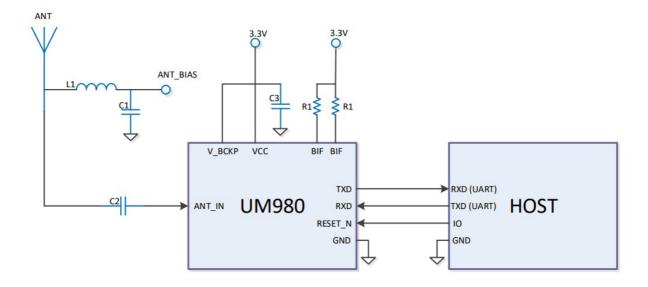


Figure 3-1 Recommended Minimal Design

L1: 68 nH RF inductor in 0603 package is recommended

C1: 100 nF + 100 pF capacitors connected in parallel is recommended

C2: 100 pF capacitor is recommended

C3: N \* 10  $\mu$ F + 1 \* 100 nF capacitors connected in parallel is recommended, and the total inductance should be no less than 30  $\mu$ F

R1: 10 k $\Omega$  resistor is recommended

### 3.2 Antenna Feed Design

UM980 just supports feeding the antenna from the outside of the module rather than from the inside. It is recommended to use devices with high power and that can withstand high voltage. Gas discharge tube, varistor, TVS tube and other high-power protective devices may also be used in the power supply circuit to further protect the module from lightning strike and surge.

If the antenna feed supply ANT\_BIAS and the module's main supply VCC use the same power rail, the ESD, surge and overvoltage from the antenna will have an effect on VCC, which may cause damage to the module. Therefore, it is recommended to design an independent power rail for the ANT\_BIAS to reduce the possibility of module damage.

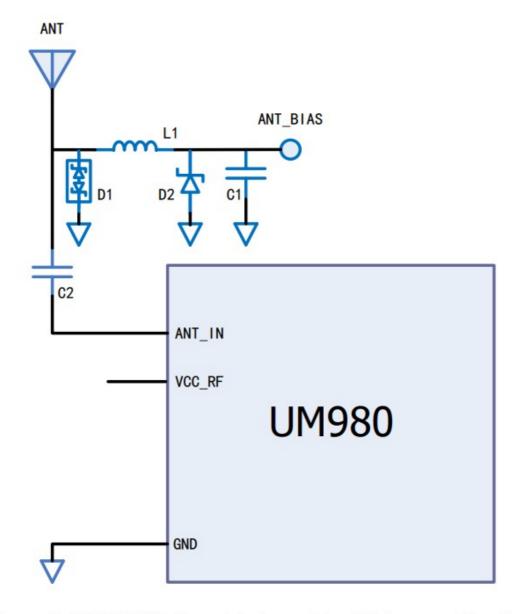


Figure 3-2 UM980 External Antenna Feed Reference Circuit

## Notes:

- L1: feed inductor, 68 nH RF inductor in 0603 package is recommended
- C1: decoupling capacitor, recommended to connect two capacitors of 100 nF/100 pF in parallel
- C2: DC blocking capacitor, recommended 100 pF capacitor
- It is not recommended to take VCC\_RF as ANT\_BIAS to feed the antenna (VCC\_RF is not optimized for antilightning strike, anti-surge and over current protection due to the compact size of the module)
- D1: ESD diode, choose the ESD protection device that supports high frequency signals (above 2000 MHz)
- D2: TVS diode, choose the TVS diode with appropriate clamping specification according to the requirement of feed voltage and antenna withstand voltage

## 3.3 Power-on and Power-off VCC

- The VCC initial level when power-on should be less than 0.4 V.
- The VCC ramp when power-on should be monotonic, without plateaus.
- The voltages of undershoot and ringing should be within 5% VCC.

- VCC power-on waveform: The time interval from 10% rising to 90% must be within 100  $\mu$ s ~1 ms.
- Power-on time interval: The time interval between the power-off (VCC < 0.4 V) to the next power-on must be larger than 500 ms.

## V\_BCKP

- The V BCKP initial level when power-on should be less than 0.4 V.
- The V BCKP ramp when power-on should be monotonic, without plateaus.
- The voltages of undershoot and ringing should be within 5% V\_BCKP.
- V BCKP power-on waveform: The time interval from 10% rising to 90% must be within 100 μs ~1 ms.
- Power-on time interval: The time interval between the power-off (V\_BCKP < 0.4 V) to the next power-on must be larger than 500 ms.

## 3.4 Grounding and Heat Dissipation

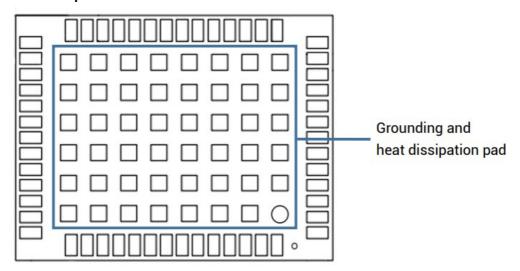


Figure 3-3 Grounding and Heat Dissipation Pad (Bottom View)

The 48 pads in the rectangle in Figure 3-3 are for grounding and heat dissipation. In the PCB design, the pads should be connected to a large sized ground to strengthen the heat dissipation.

## 3.5 Recommended PCB Package Design

See the following figure for the recommended PCB package design.

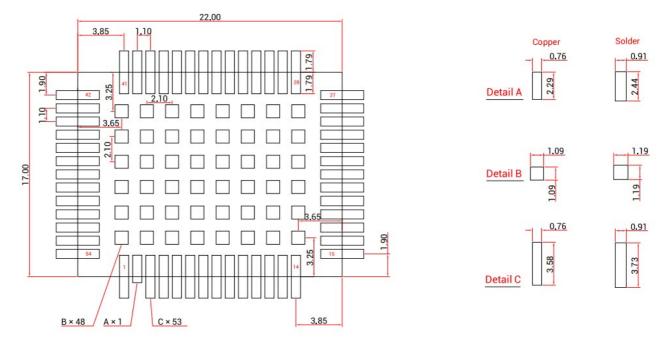


Figure 3-4 Recommended PCB Package Design

#### Notes:

For the convenience of testing, the soldering pads of the pins are designed long, exceeding the module border much more. For example:

- The pads denoted as detail C are 1.79 mm longer than the module border.
- The pad denoted as detail A is 0.50 mm longer than the module border. It is relatively short as it is an RF pin pad, so we hope the trace on the surface is as short as possible to reduce the impact of external interference on the RF signals.

## **Production Requirement**

Recommended soldering temperature curve is as follows:

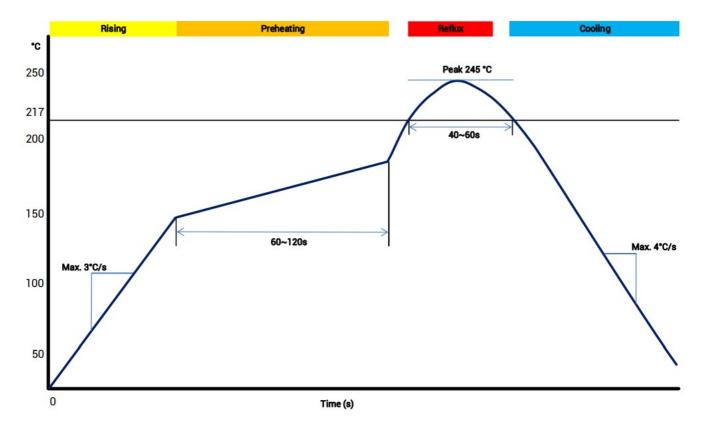


Figure 4-1 Soldering Temperature (Lead-free)

## **Temperature Rising Stage**

• Rising slope: Max. 3 ° C/s

• Rising temperature range: 50 ° C ~ 150 °C

## **Preheating Stage**

• Preheating time: 60s ~ 120 s

• Preheating temperature range: 150 °C ~ 180 °C

## **Reflux Stage**

• Over melting temperature (217 °C) time: 40s ~ 60 s

• Peak temperature for soldering: no higher than 245 °C



## Cooling Stage

- Cooling slope: Max. 4 °C / s
- In order to prevent falling off during soldering of the module, do not solder it on the back of the board during design, and it is not recommended to go through soldering cycle twice.
- The setting of soldering temperature depends on many factors of the factory, such as board type, solder paste type, solder paste thickness etc. Please also refer to the relevant IPC standards and indicators of solder paste.
- Since the lead soldering temperature is relatively low, if using this method, please give priority to other components on the board.

• The opening of the stencil needs to meet your design requirement and comply with the examine standards. The thickness of the stencil is recommended to be 0.15mm.

## **Packaging**

## 5.1 Label Description



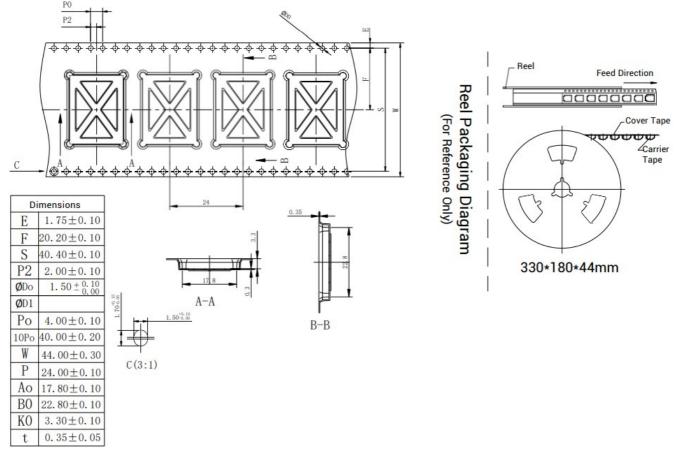
Figure 5-1 Label Description

## **5.2 Product Packaging**

The UM980 module uses carrier tape and reel (suitable for mainstream surface mount devices), packaged in vacuum-sealed aluminum foil antistatic bags, with a desiccant inside to prevent moisture. When using reflow soldering process to solder modules, lease strictly comply with IPC standard to conduct temperature and humidity control on the modules. As packaging materials such as the carrier tape can only withstand the temperature of 55 degrees Celsius, modules shall be removed from the package during baking.



Figure 5-2 UM980 Package



#### Note:

- 1. The cumulative tolerance of 10 side holes should not exceed  $\pm$  0.2 mm.
- 2. Material of the tape: Black antistatic PS (surface impedance 10 5 -10 11 ) (surface static voltage <100 V), thickness: 0.35 mm.
- 3. Total length of the 13-inch reel package: 6.816 m (Length of the first part of empty packets: 0.408 m, length of packets containing modules: 6 m, length of the last part of empty packets: 0.408 m).
- 4. Total number of packets in the 13-inch reel package: 284 (Number of the first part of empty packets: 17; actual number of modules in the packets: 250; number of the last part of empty packets: 17).
- 5. All dimension designs are in accordance with EIA-481-C-2003.
- 6. The maximum bending degree of the carrier tape within the length of 250 mm should not exceed 1 mm (see the figure below).

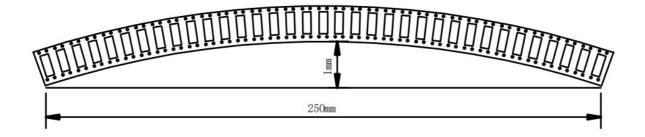


Figure 5-3 UM980 Reel Package Diagram

Item	Description	
Module Number	250 pieces/reel	
Reel Size	Tray: 13" External diameter: 330 ± 2 mm, Internal diameter: 180 ± 2mm, Width: 44.5 ± 0.5 mm Thickness: 2.0 ± 0.2 mm	
Carrier Tape	Space between (center-to-center distance): 24 mm	

Before surface mounting, make sure that the color of the 30% circle on the HUMIDITY INDICATOR is blue (see Figure 5-4). If the color of the 20% circle is pink and the color of the 30% circle is lavender (see Figure 5-5), you must bake the module until it turns to blue. The UM980 is rated at MSL level 3. Please refer to the IPC/JEDEC J-STD-033 standards for the package and operation requirements. You may also access to the website <a href="https://www.jedec.org">www.jedec.org</a> to get more information.

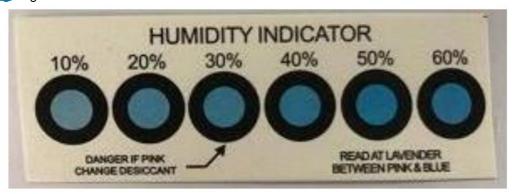


Figure 5-4 Normal Humidity Indication

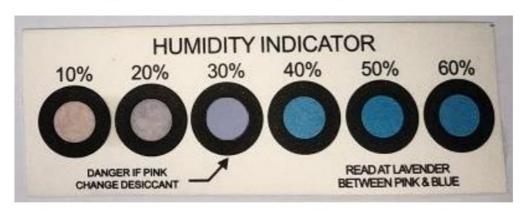


Figure 5-5 Abnormal Humidity Indication

The shelf life of the UM980 module packaged in vacuum-sealed aluminum foil antistatic bags is one year.



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## **Documents / Resources**



## unicore UM980 All Constellation Multi Frequency High Precision RTK Positioning Module [pdf] Instruction Manual

UM980 All Constellation Multi Frequency High Precision RTK Positioning Module, UM980, All C onstellation Multi Frequency High Precision RTK Positioning Module, Constellation Multi Frequency High Precision RTK Positioning Module, Multi Frequency High Precision RTK Positioning Module, Frequency High Precision RTK Positioning Module, High Precision RTK Positioning Module, Precision RTK Positioning Module, RTK Positioning Module

## References

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